PATENT

AF/3700

Case Docket No. IIDAP10.001AUS
Date: November 6, 2002

Applicant	:	Miyoshi, Takashi
App. No.	:	09/844,155
Filed	:	April 27, 2001
For	:	COPPER ALLOY SUITABLE FOR AN IC LEAD PIN FOR A PIN GRID ARRAY PROVIDED ON A PLASTIC SUBSTRATE
Examiner	:	Ip, Sikyin
Art Unit	:	1742

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first class mail in an envelope addressed to: United States Patent and Trademark Office, P.O. Box 2327, Arlington, VA 22202, on

November 6, 2002
(Date)

Thomas R. Arno, Reg. No. 40,490

UNITED STATES PATENT AND TRADEMARK OFFICE BOX AF
P.O. Box 2327
Arlington, VA 22202

Sir:

Transmitted herewith is an amendment in the above-identified application.

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(X) Please use Customer No. 20,995 for the correspondence address.

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IIDAP10.001AUS PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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AMENDMENT AFTER FINAL

United States Patent and Trademark Office
P.O. Box 2327
Arlington, VA 22202

Dear Sir:

In response to the Office Action dated August 7, 2002, please amend the above captioned patent application as set forth below.

IN THE CLAIMS:

Please cancel Claim 7. Please amend Claims 1-4 as follows:

1. (Amended) A copper alloy suitable for an IC lead pin for a pin grid array provided on a plastic substrate, wherein the copper alloy is selected from the group consisting of:

a copper alloy consisting essentially of 0.05 to 0.5 wt% of Zn and 0.05 to 0.5 wt% of Mg, with the balance being made of unavoidable impurities and Cu;

a copper alloy consisting essentially of 0.1 to 1.0 wt% of Sn, with the balance being made of unavoidable impurities and Cu; and

a copper alloy consisting essentially of 0.1 to 1.0 wt% of Sn and 0.1 to 0.6 wt% of Ag, with the balance being made of unavoidable impurities and Cu;

wherein the copper alloy has conductivity of 50% IACS or more, and tensile stress of 400 MPa or more but 650 MPa or less.